Electronic Patent Application Fee Transmittal							
Application Number:	106	10622001					
Filing Date:	17-Jul-2003						
Title of Invention:	Electro-chemical deposition system and method of electroplating on substrates						
First Named Inventor/Applicant Name:	Uziel Landau						
Filer:	Ya-Fen Chen/Robyne Orlando						
Attorney Docket Number:	AMAT/2601.R02/CPI/COPPER/						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
	Tota	180		